

ADHESIVE COMPOSITION

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Abstract

PURPOSE: To obtain a cold-setting adhesive composition showing sufficient adhesiveness to dentine and having a high curing rate by combining a polymerizable monomer with a polymerization initiator containing a specified peroxide.

CONSTITUTION: A polymerizable monomer [e.g. methyl (meth)acrylate, ethylene glycol or (meth)acrylic acid] is mixed with a polymerization initiator containing a peroxide of formula I, II or III [wherein R1, R2, and R3 are each H, alkyl, (substituted) phenyl or (substituted) cyclohexyl; X is allylene, vinylene or phenylene; Y is carboxyl, an acid anhydride group, a phosphate group or a borate group; P is (substituted) alkylene] (e.g. a compound of formula IV, V or VI), having an adhesive composition. This composition has excellent curability near ordinary temperature and is effective particularly as dental adhesive. It can also be used in other applications, such as adhesives for the artificial bone and for metal.

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